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CEDA 7000.5  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Brian Lewis  
Serial No. 10/722,288  
Filed November 25, 2003  
For THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS

February 26, 2004

COMMISSIONER FOR PATENTS  
P.O. BOX 1450  
ALEXANDRIA, VIRGINIA 22313-1450

SIR:

**INFORMATION DISCLOSURE STATEMENT**

In accordance with 37 C.F.R. 1.97 and 1.98 and MPEP 609, and in compliance with the duty of disclosure set forth in 37 C.F.R. 1.56, applicant submits the attached PTO/SB/08A for consideration by the Patent and Trademark Office in the above-entitled application and to be made of record therein.

Applicant is not submitting copies of any of the documents listed on the attached form because such copies were provided in 10/151,741, now 6,653,741, relied on for priority, and because such copies are excused by Rule 1.98(d). But if the examiner requires any copies, please call the undersigned and he will fax or mail them as requested.

Respectfully submitted,

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PTO/SB/08A

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

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**Complete if Known**

Application Number 10/722,288

Filing Date November 25, 2003

Confirmation Number

First Named Inventor Brian Lewis

Group Art Unit

Examiner Name

Sheet

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Attorney Docket No.

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**U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code <sup>2</sup> (if known)		
	1	3,996,548	A	Chaffin	12-1976
	2	4,670,770	A	Tai	06-1987
	3	4,819,857	A	Mizuishi et al.	04-1989
	4	4,954,870	A	Takemura et al.	09-1990
	5	5,023,697	A	Tsumura	06-1991
	6	5,082,162	A	Kamiyama et al.	01-1992
	7	5,097,387	A	Griffith	03-1992
	8	5,240,172	A	Steinke et al.	08-1993
	9	5,242,658	A	Stevens et al.	09-1993
	10	5,256,370	A	Slattery et al.	10-1993
	11	5,306,950	A	Fujikawa et al.	04-1994
	12	5,471,092	A	Chan et al.	11-1995
	13	5,552,234	A	Kawasumi	09-1996
	14	5,635,764	A	Fujikawa et al.	06-1997
	15	5,755,896	A	Paruchuri et al.	05-1998
	16	5,938,862	A	Yeh et al.	08-1999

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<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached or place an "A" here if English language abstract is attached..

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	17	6,047,876	A	Smith	04-2000
	18	6,059,900	A	Gayle et al.	05-2000
	19	6,176,947	B1	Hwang et al.	01-2001
	20	6,205,264	B1	Jin et al.	03-2001
	21	6,231,693	B1	Lugscheider et al.	05-2001
	22	6,306,516	B1	Jin et al.	10-2001
	23	6,319,617	B1	Jin et al.	11-2001
	24	6,326,685	B1	Jin et al.	12-2001
	25	6,365,973	B1	Koning	04-2002

**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T <sup>6</sup>
		Office	Number <sup>4</sup>	Kind Code <sup>2</sup> (if known)			
	26	EP	1 153 698	A1		11-2001	
	27	JP	62-212095	A		09-1987	
	28	JP	62-263895			11-1987	
	29	JP	9-172224			06-1997	
	30	JP	11-26335			01-1999	
	31	NL	9200564	A		10-1993	
	32	WO	99/02299			01-1999	

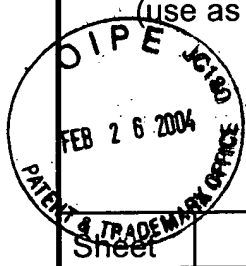
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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		Application Number	10/722,288
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		First Named Inventor	Brian Lewis
		Group Art Unit	
		Examiner Name	
Sheet 3 of 3	Attorney Docket No.	CEDA 7000.5	



	33	WO	01/34860			05-2001	
<b>OTHER ART - NON PATENT LITERATURE DOCUMENTS</b>							
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.) date, page(s), volume-issue number(s), publisher, city and/or country where published.					T <sup>6</sup>
	34	HAREESH MAVORRI et al, Universal Solders for Direct and Powerful Bonding on Semiconductors, Diamond, and Optical Materials, Applied Physics Letter, May 7, 2001, pp. 2976-2978 vol. 78, No. 19.					
	35	International Search Report, PCT/US02/15870, dated Apr. 10, 2003, 4 pages.					

Examiner Signature		Date Considered	
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